

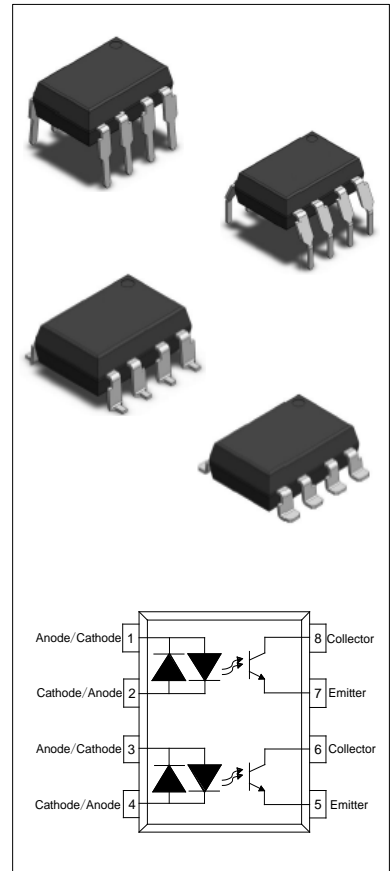


JOC824X Series

Rev.A.1.0

DESCRIPTION:

The JOC824X series combine two AlGaAs infrared emitting diodes as the AC input which is optically coupled to a silicon planar phototransistor detector in a plastic DIP8 package with different lead forming options. With the robust coplanar double mold structure, JOC824X series provide the most stable isolation feature. The products are widely used in AC line monitor, programmable controllers, telephone line interface, system appliance and measurement instrument.



MAIN FEATURES

- High isolation 5000 VRMS
- CTR flexibility available see order information
- AC input with transistor output
- Operating temperature range -55°C to 110°C
- REACH compliance
- Halogen free
- MSL class1
- UL、VDE、CQC approvals

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	± 60	mA
	Peak Forward Current	I_{FP}	$\pm 1^{①}$	A
	Power Dissipation	P_I	100	mW
Output	Collector-emitter Voltage	V_{CEO}	80	V
	Emitter-collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_O	150	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	5000 ^②	Vrms
Operating Temperature		T_{opr}	-55~+110	°C

Storage Temperature	T _{stg}	-55~+125	°C
Soldering Temperature	T _{sol}	260	°C

NOTE1: 100μs pulse, 100Hz frequency

NOTE2: AC for 1minute, R.H.=40~60%

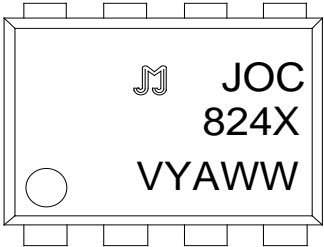
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V _F	I _F =±10mA	-	1.24	1.4	V
			I _F =±20mA	-	1.3	1.5	
	Input Capacitance	C _{in}	V=0, f=1MHz	-	30	250	pF
Output	Collector-Emitter dark current	I _{CEO}	V _{CE} =20V, I _F =0	-	-	50	nA
	Collector-Emitter breakdown voltage	BV _{CEO}	I _C =0.1mA I _F =0	80	-	-	V
	Emitter-Collector breakdown voltage	BV _{ECO}	I _E =0.1mA I _F =0	6	-	-	V
Transfer Characteristics	Current transfer ratio	CTR ^①	I _F =±1mA V _{CE} =5V	20	-	400	%
	Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _F =±20mA I _C =1mA	-	0.06	0.2	V
	Isolation resistance	R _{IO}	DC500V 40~60%R.H.	10 ¹²	10 ¹⁴	-	Ω
	Floating Capacitance	C _{IO}	V=0, f=1MHz	-	0.4	1	pF
	Cut-off Frequency	f _c	V _{CE} =5V, I _C =2mA R _L =100Ω, -3dB	-	80	-	kHz
	Rise Time	t _r	V _{CE} =2V, I _C =2mA R _L =100Ω	-	4	18	μs
	Fall Time	t _f		-	5	18	μs
	Response Time	t _{on}		-	8	25	μs
t _{off}		-		6	25	μs	

NOTE1: Rank Table of Current Transfer Ratio (Temperature=25°C)

Grade Sign	Min. (%)	Max. (%)
None	20	400
A	50	150
B	80	400

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
		JOC : Company Abbr. 824 : Part Number X : CTR Rank V: VDE Option Y : Fiscal Year A : Manufacturing Code WW : Work Week	
ORDERING INFORMATION			
JOC824X(Y)(Z)-GV			
JOC – Company Abbr. 824– Part Number X – Rank (A/B/None) Y– Lead Form Option (M/S/SL/None) Z – Tape and Reel Option (T1/T2) G – Green V – VDE Option (V or None)			
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
None/M	45 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =14.4k Units
S(T1/T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SL(T1/T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

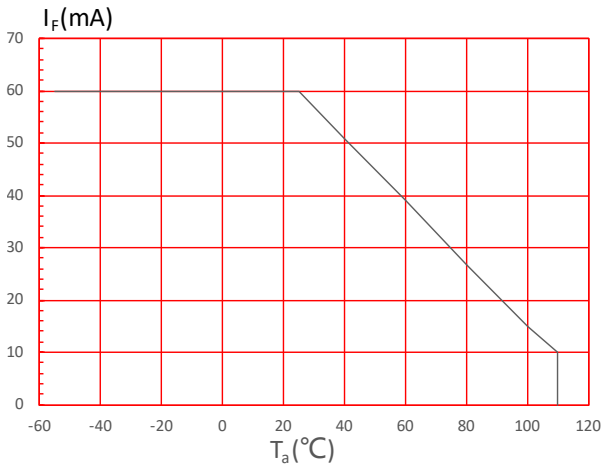


FIG.2: Collector Power Dissipation vs. Ambient Temperature

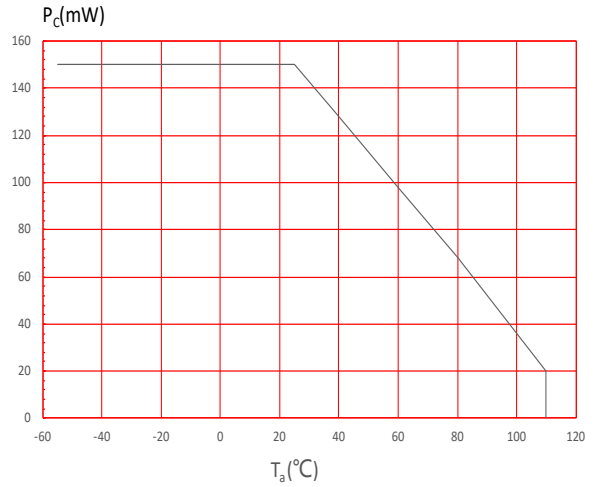


FIG.3: Forward Current vs. Forward Voltage

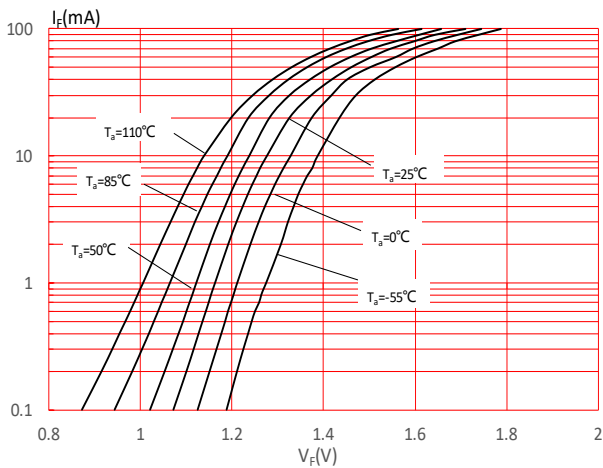


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

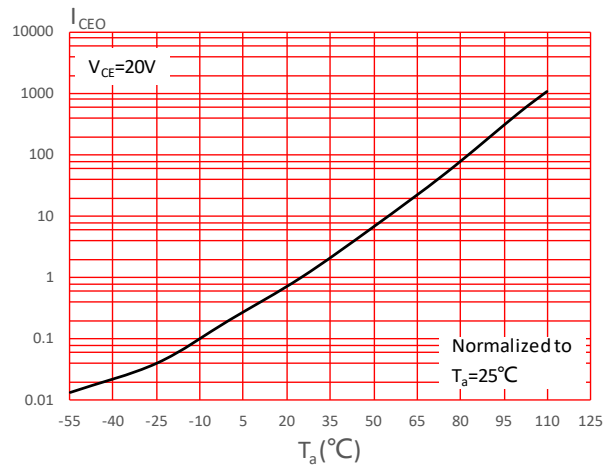


FIG.5: Collector Current vs. Collector-emitter Voltage

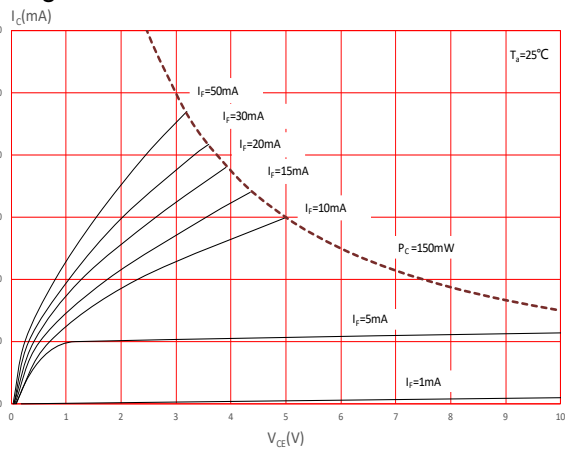


FIG.6: Normalized Current Transfer Ratio vs. Forward Current

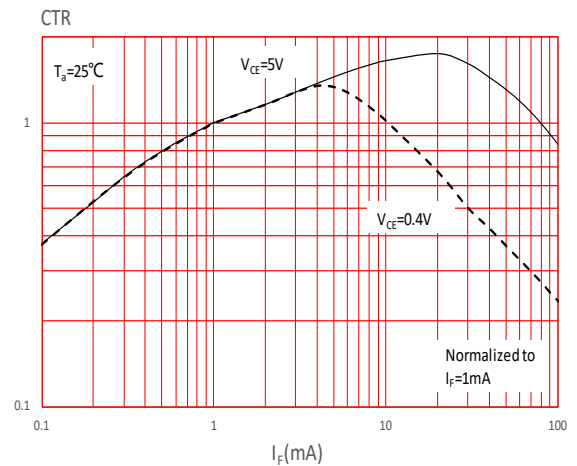


FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

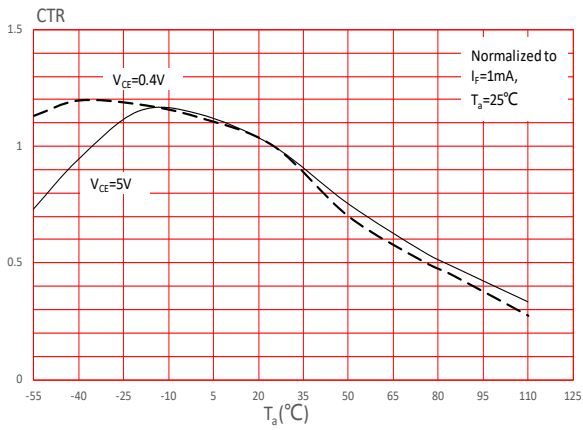


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

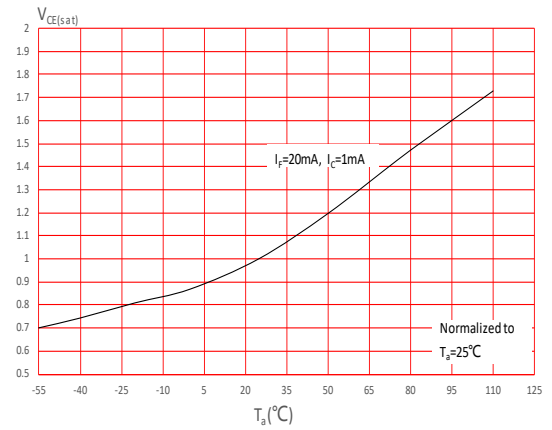


FIG.9: Response Time vs. Load Resistance

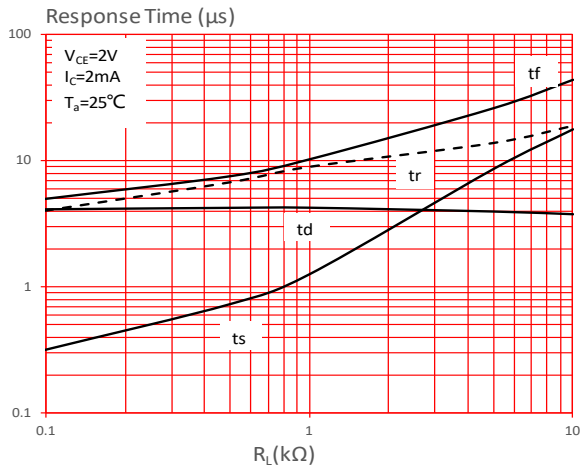
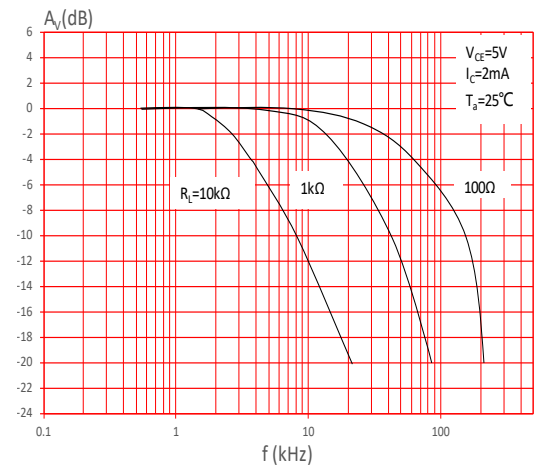


FIG.10: Frequency Response



Test Circuits

FIG.11: Test Circuits of Response Time

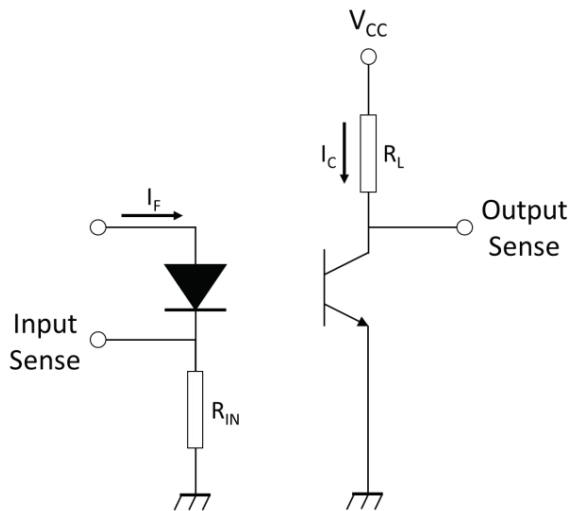


FIG.12: Curves of Response Time

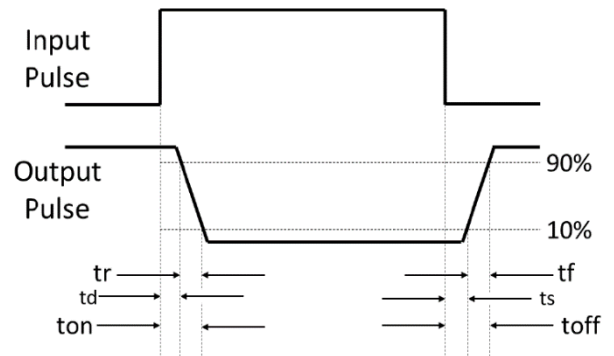
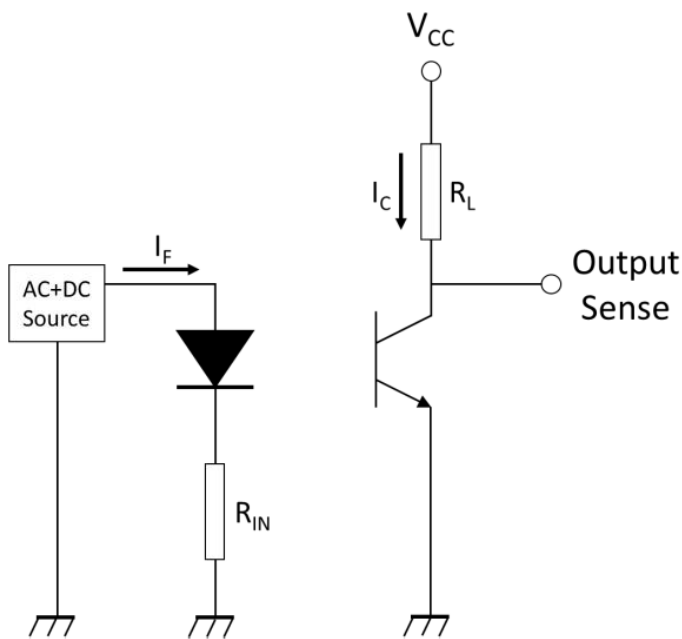
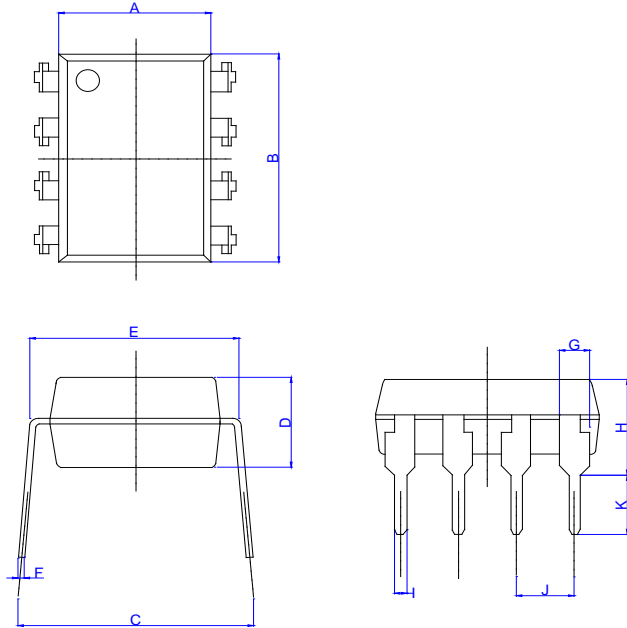


FIG.13: Test Circuits of Frequency Response



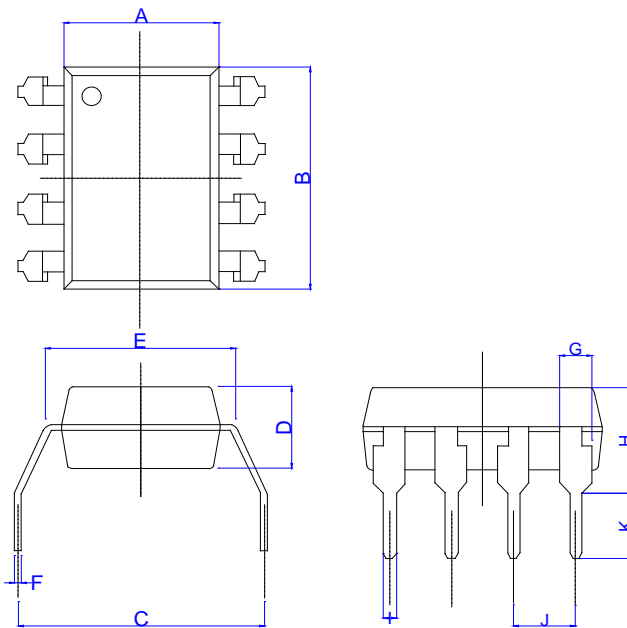
Package Dimension (Unit: mm)

Standard DIP Type:



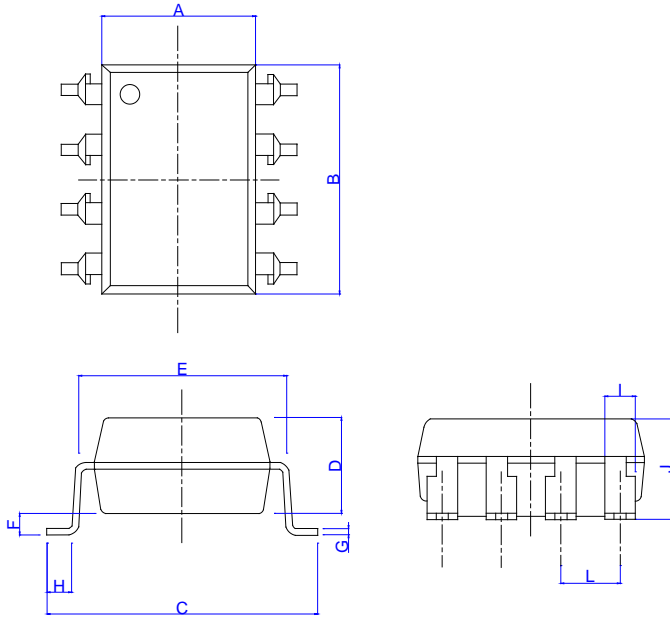
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	9.36		9.96	0.369		0.392
C	7.62		10.16	0.300		0.400
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.16		0.36	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.50		4.80	0.138		0.189
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.40		3.40	0.094		0.134

Option M Type:



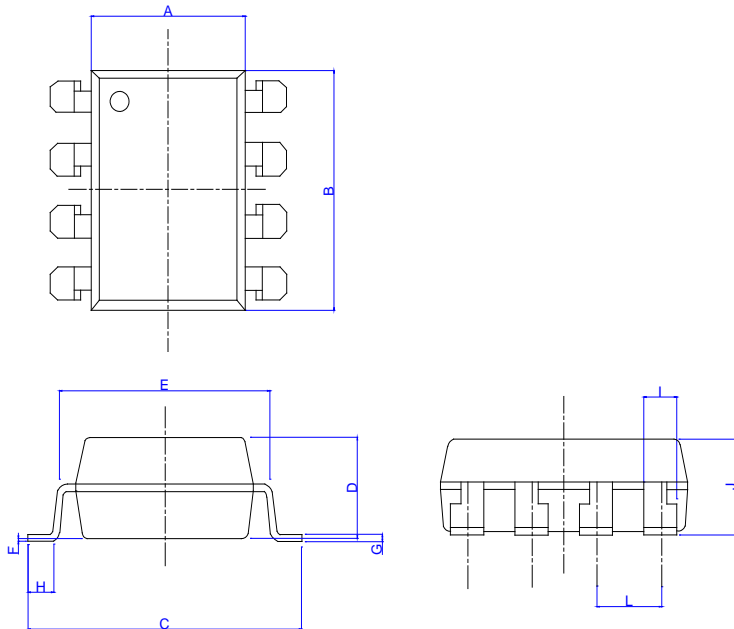
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.40		6.80	0.252		0.268
B	9.56		9.96	0.376		0.392
C	9.86		10.46	0.388		0.412
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F		0.25			0.010	
G	1.20		1.40	0.047		0.055
H	4.28		4.88	0.169		0.192
I		0.50			0.020	
J		2.54			0.100	
K		2.20			0.087	

Option S Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.40		6.80	0.252		0.268
B	9.56		9.96	0.376		0.392
C	9.85		10.45	0.388		0.412
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F		0.80			0.031	
G		0.25			0.010	
H		0.80			0.031	
I	1.20		1.40	0.047		0.055
J	4.00		4.60	0.157		0.181
L		2.54			0.100	

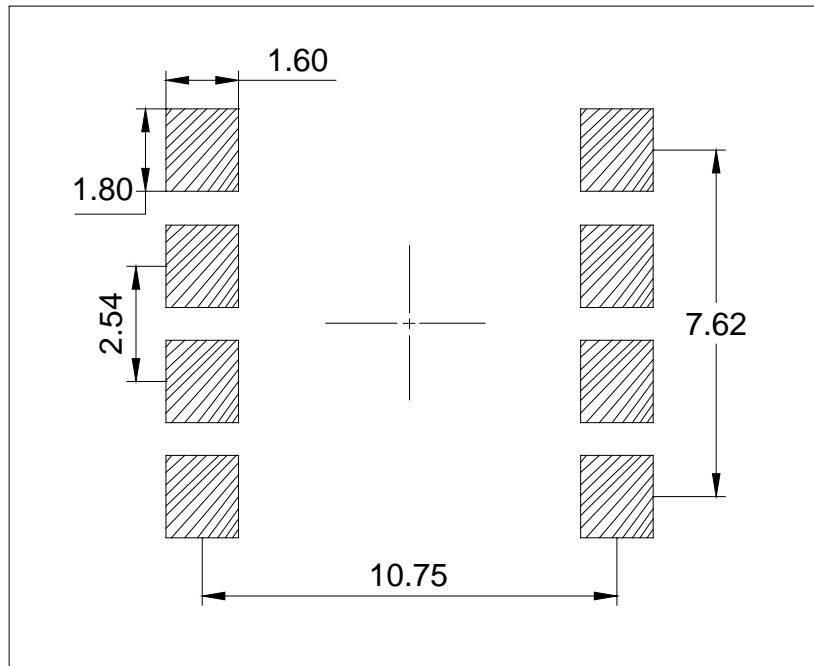
Option SL Type:



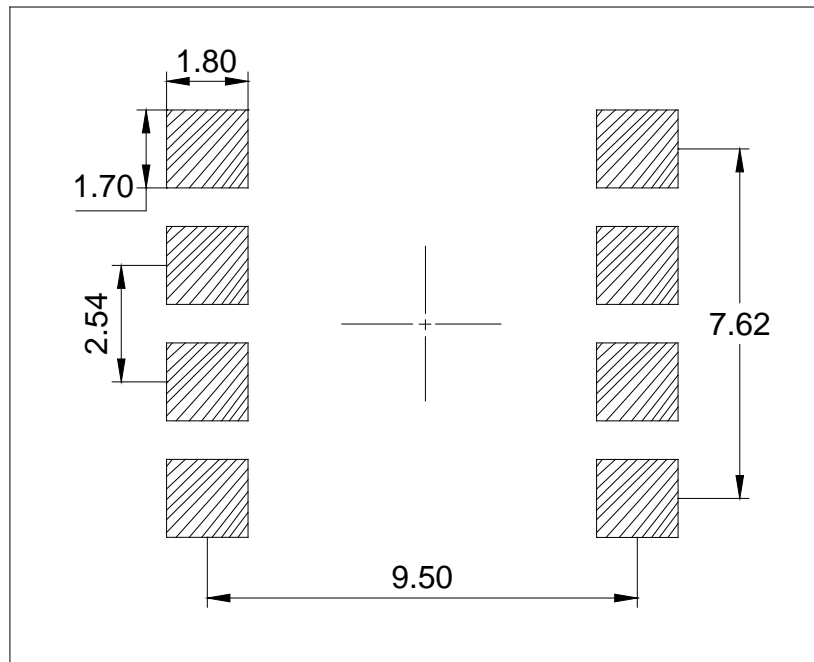
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	9.36		9.96	0.369		0.392
C	9.50		10.45	0.374		0.411
D	3.00		4.00	0.118		0.157
E	7.32		7.92	0.288		0.312
F	0.10		0.65	0.004		0.026
G	0.16		0.36	0.006		0.014
H	0.80		1.40	0.031		0.055
I	0.90		1.50	0.035		0.059
J	3.30		4.35	0.130		0.171
L	2.29		2.79	0.090		0.110

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option S

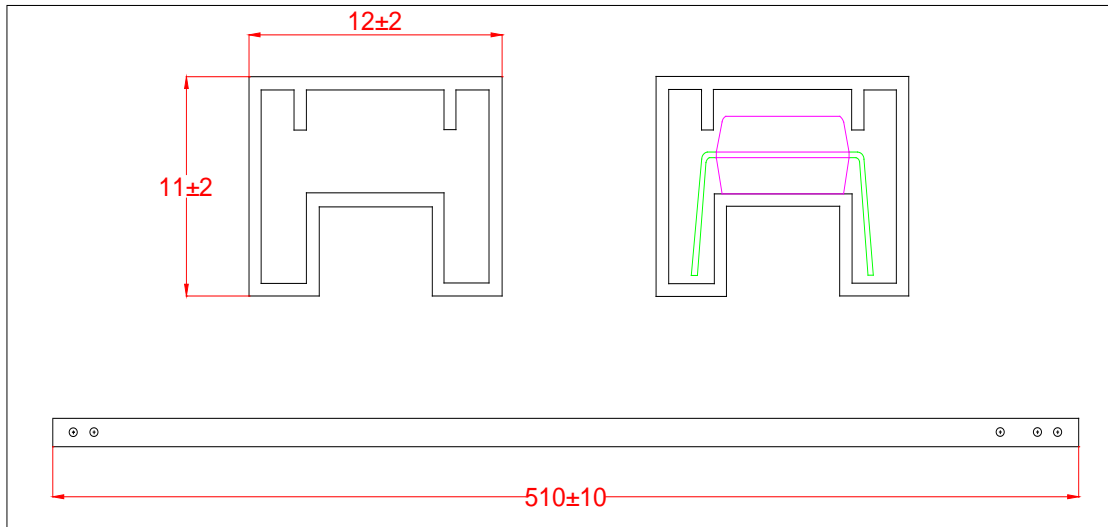


Option SL

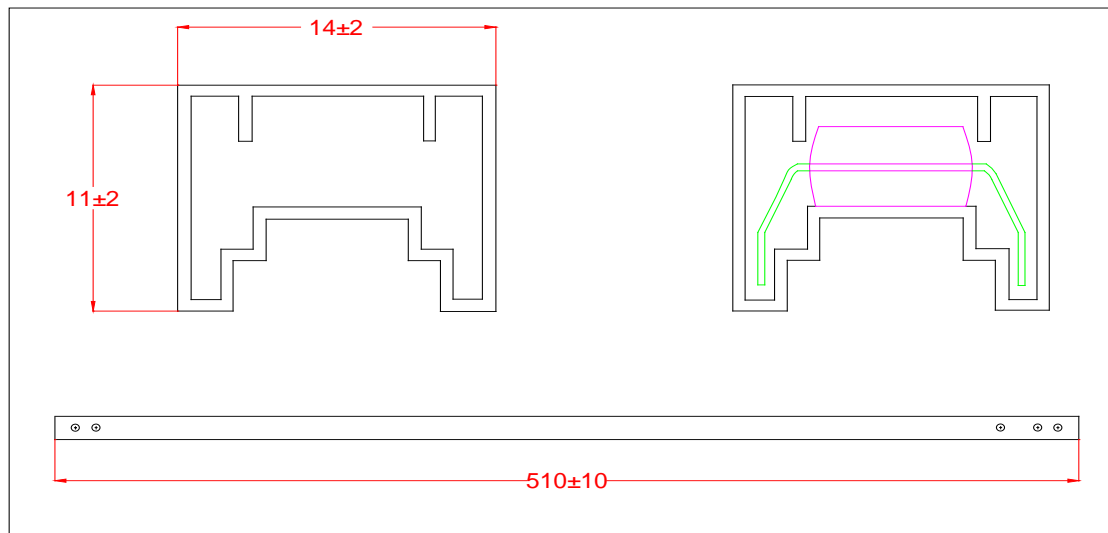


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

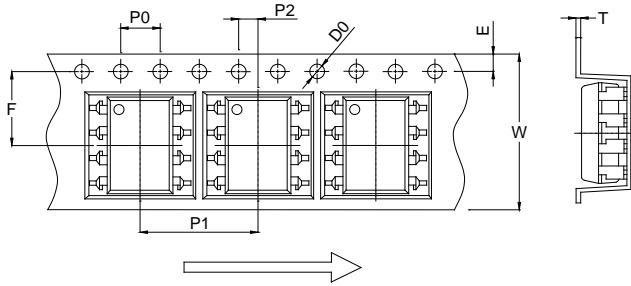


Option M

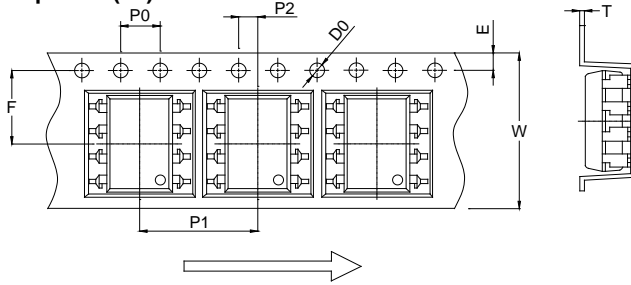


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1)

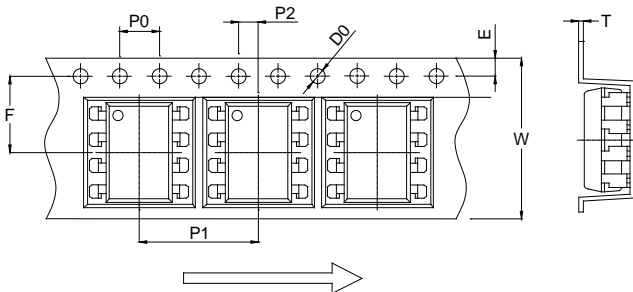


Option S(T2)

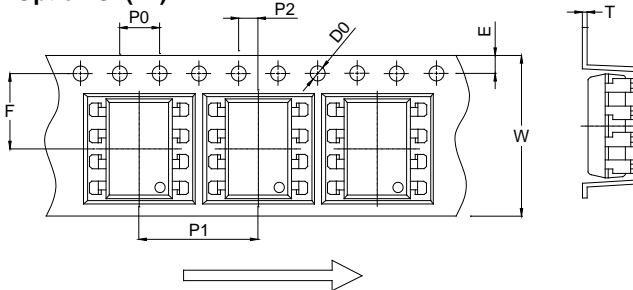


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.65		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

Option SL(T1)

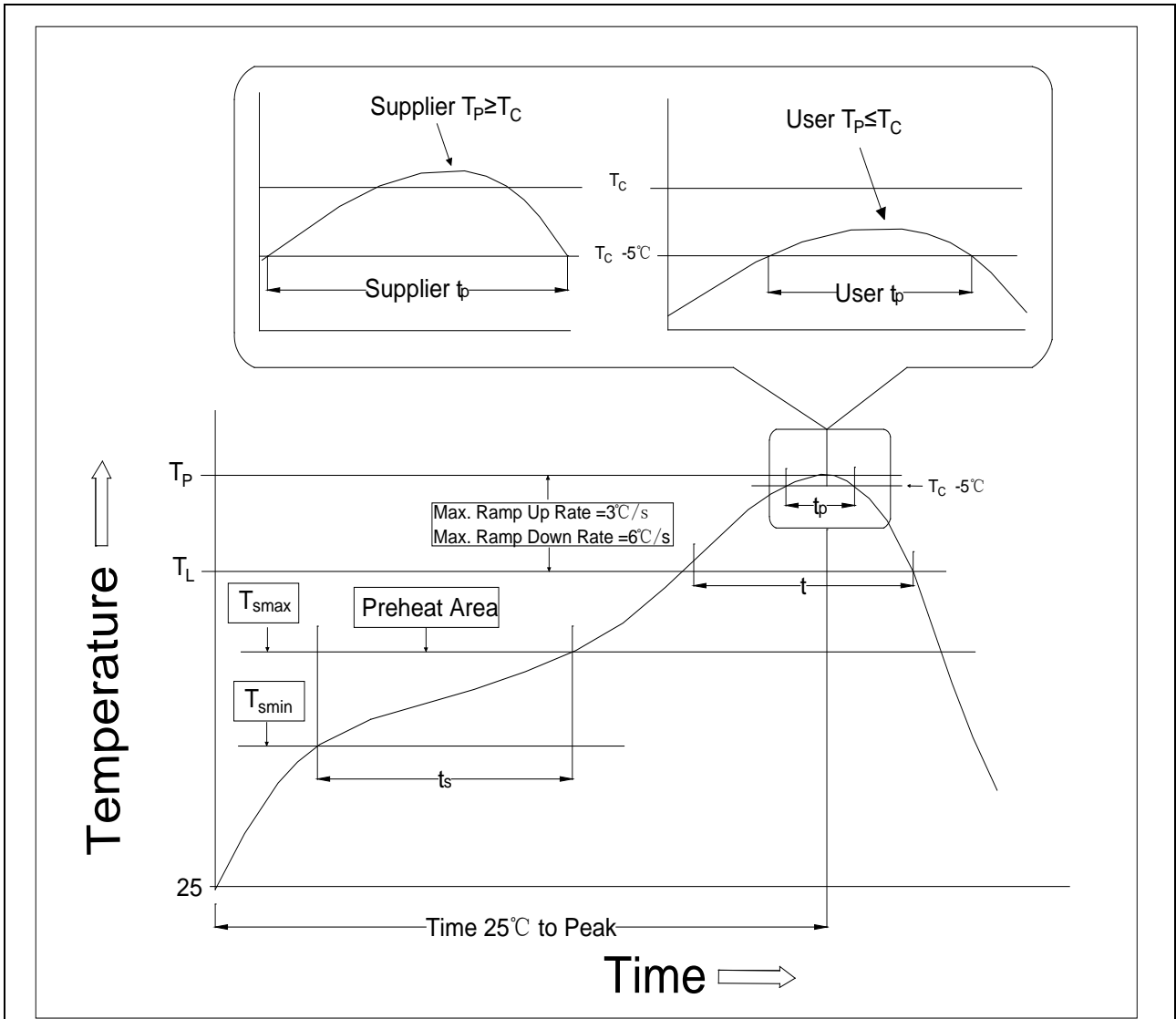


Option SL(T2)



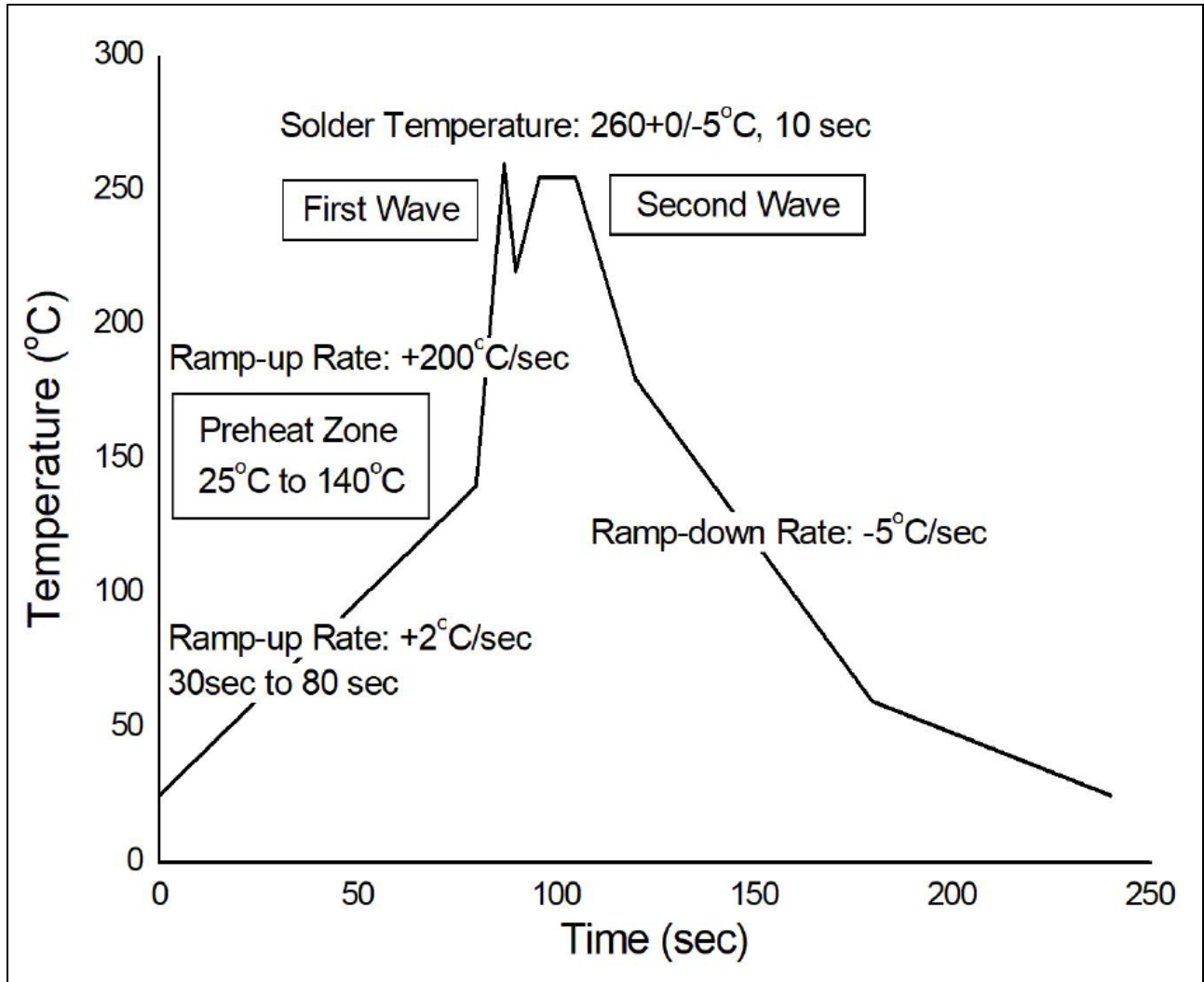
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360±5°C
Soldering Time	3s max.

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